A thermosetting resin generally must be cured at a temperature of 100°C or greater. As a result, gaps are typically generated due to different coefficients of thermal expansion among the seal resin 8, the lead terminal 4, and the resin material casing 3 when the temperature of the seal resin 8 is restored to room temperature after that seal resin has been cured at the high curing temperature. Adequate hermetic sealing therefore cannot be ensured.

Claim 15 of the present application specifies that an anaerobic adhesive is filled in gaps between metallic terminals and resin material after integrally molding the resin material with the metallic terminals. Claim 17, moreover, requires the anaerobic adhesive to be filled as specified after integrally molding an outer resin case with the metallic lead members. In the context of the present invention, an anaerobic adhesive is an adhesive which, instead of being cured upon exposure to air, is cured only at portions thereof which contact metal in a sealed space. An anaerobic adhesive as defined by both claim 15 and claim 17, therefore, is significantly different from the adhesive utilized in the Saito et al. procedure, and can be cured without heating at a high temperature. Such an adhesive thus avoids gap generation such as that mentioned and ensures adequate hermetic sealing.

Claim 18 of the present application specifies that a high-permeability adhesive is filled in gaps between metallic terminals and resin material after integrally molding the resin material with the metallic terminals, while claim 20 specifies that the high-permeability adhesive is so filled in after integrally molding an outer resin case with metallic end members. The Saito et al. publication does not suggest that the seal resin 8 is a high-permeability adhesive

as claims 18 and 20 require. Such a high-permeability adhesive has a low viscosity and thus differs from the Saito et al. seal resin formed of a high-hardness gel or adhesive.

For reasons discussed above, it is respectfully submitted that none of claims 15, 17, 18, and 20 is in fact anticipated by the Saito et al. publication discussed by the Examiner. Nothing noted by the Examiner, moreover, suggests modifying the Saito et al. pressure sensor so that it incorporates either an anaerobic adhesive or a high-permeability adhesive as discussed, and it is further submitted that each of the claims mentioned is patentable.

Claims 16 and 19 are rejected under 35 U.S.C. §103(a) as unpatentable over the Saito et al. publication mentioned. Reconsideration of this rejection is also requested. The Saito et al. disclosure teaches that the seal resin 8 is a flurosilicone gel, a fluoride gel, a polyphenylene sulfide resin, or a synthetic resin adhesive providing superior adhesion to a lead terminal. Nothing in the Saito et al. disclosure, however, suggests that the seal resin 8 as an anaerobic adhesive. Claims 16 and 19 of the present application specify that the anaerobic adhesive is polymethacrylic adhesive. Nothing noted by the Examiner in any way suggests that a polymethacrylic adhesive is either "the most optimum adhesive" or even suitable for use in the Saito et al. pressure sensor, and the rejection of claims 16 and 19 set forth on page 4 of the Office Action is inappropriate.

All of claims 15-20 as they presently appear in this application are considered allowable for reasons discussed above. If there are any questions regarding this Reply or the application in general, a telephone call to the

undersigned would be appreciated since this should expedite the prosecution of the application for all concerned.

If necessary to effect a timely response, this paper should be considered as a petition for an extension of time sufficient to effect a timely response. Please charge any deficiency in fees or credit any overpayments to Deposit Account No. 05-1323 (Docket #056205.55095US).

Respectfully submitted,

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